

EAST - [10660102.wsp:1]

File View Edit Tools Window Help

Drafts
Pending
Active
L1: (407) (chip near on near film COF) and ((substrate insulating near tape) with (heat\$3 pre-he...
L2: (5) (chip near on near film COF) and ((insulating near tape) with (heat\$3 pre-heat\$3 cure cu...
L3: (2) ((chip near on near film COF) and ((insulating near tape) with (heat\$3 pre-heat\$3 cure c...
L4: (5) ((chip near on near film COF) and ((insulating near tape) with (heat\$3 pre-heat\$3 cure c...
Failed
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UDC
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Default open Highlight all hit terms initially

((chip near on near film COF) and
((insulating near tape) with (heat\$3
pre-heat\$3 cure curing light\$3))) and
resin

BR... IS... m... 3 Fed HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	R
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20040063332 A1	20040401	14	COF semiconductor device and a manufacturing method for the same	438/734		
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20010008303 A1	20010719	31	Semiconductor apparatus, a method of fabrication of the same, and a reinforcing	257/666	257/668; 257/670;	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6740966 B2	20040525	31	Semi-conductor apparatus, a method of fabrication of the same, and a reinforcing	257/701	257/668; 257/678;	
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6313526 B1	20011106	29	Semiconductor apparatus, Including thin film belt-like insulating tape	257/706	206/714; 206/716;	
5	<input type="checkbox"/>	<input type="checkbox"/>	JP 2004128337 A	20040422	11	COF SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD			